## **IN THE CLAIMS:**

| 1. (Currently amended) A method for the mitigation of $\underline{a}$ topological |
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| defects of an optical material, defect of a substrate, comprising:                |
| providing a substrate with a topological defect;                                  |
| depositing material comprising at least one layer of amorphous                    |
| material onto said substrate; and   |
| wherein said optical material comprises at least one layer of amorphous material, |
| the method comprising   |
| planarizing with an ion beam only said at least one layer of amorphous            |
| material to mitigate said topological defect of said substrate.                   |
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| 2. (Original) The method of claim 1, wherein said at least one layer of           |

3. (Original) The method of claim 1, wherein said at least one layer of amorphous material comprises a layer of silicon on a substrate.

amorphous material comprises at least one layer of silicon.

4. (Original) The method of claim 1, further comprising depositing said at least one layer of amorphous material onto a substrate prior to the step of planarizing.

- 5. (Original) The method of claim 4, wherein said at least one layer of amorphous material comprises a plurality of layers of amorphous material, the method further comprising planarizing each layer of said plurality of layers of amorphous material.
- 6. (Original) The method of claim 4, wherein the step of depositing said at least one layer of amorphous material is carried out with a primary ion beam and wherein the step of planarizing is carried out with a secondary ion beam.
- 7. (Currently amended) The method of claim 1, wherein said optical material comprises a bi-layer of optical material on a substrate, wherein said at least one layer of amorphous material forms one layer of said bi-layer and has an index of refraction that is less than a material that forms another layer of said bi-layer.
- 8. (Currently amended) The method of claim 2, wherein said optical material comprises a bi-layer of optical material on a substrate, wherein said at least one layer of silicon forms one layer of said bi-layer and wherein molybdenum forms another layer of said bi-layer.

- 9. (Currently amended) The method of claim 2, wherein said optical material comprises a bi-layer of optical material on a substrate, wherein said at least one layer of silicon forms one layer of said bi-layer and wherein beryllium forms another layer of said bi-layer.
- 10. (Original) The method of claim 2, wherein said at least one layer of silicon is an element of an EUV reticle.
- 11. (Original) The method of claim 1, wherein said at least one layer of amorphous material is deposited by ion beam sputtering at near-normal incidence and then subsequently etched by a secondary ion source at near-normal incidence.
- 12. (Original) The method of claim 2, wherein said at least one layer of silicon is deposited by ion beam sputtering with a primary ion beam at an energy within a range from about 400-2000 eV.
- 13. (Original) The method of claim 9, wherein the step of planarizing is carried out with an ion beam having an ion beam energy in the range from about 50–2000 eV.

- 14. (Original) The method of claim 6, wherein at least one of said primary ion beam and said secondary ion beam comprises a source gas selected from the group consisting of Argon, Krypton, Neon and Xenon.
- 15. (Original) The method of claim 1, wherein the step of planarizing includes directing an ion beam onto said at least one layer of amorphous material to remove a fraction of the layer between the values of 0.05 and 1.
- 16. (Currently amended) An EUV reticle, comprising:

  a substrate with a topological defect;

  a bi-layer of optical material on a said substrate, wherein at least one layer of amorphous material forms one layer of said bi-layer and has an index of refraction that is less than a material that forms another layer of said bi-layer, wherein only said at least one layer of amorphous material has been planarized with an ion beam to mitigate said toplogocal defect.
- 17. (Previously presented) The EUV reticle of claim 16, wherein said at least one layer of amorphous material comprises at least one layer of silicon.
- 18. (Previously presented) The EUV reticle of claim 16, wherein said at least one layer of amorphous material comprises a plurality of layers of

amorphous material, wherein each layer of said plurality of layers of amorphous material has been planarized.

- 19. (Previously presented) The EUV reticle of claim 17, wherein said at least one layer of silicon forms one layer of said bi-layer and wherein molybdenum forms another layer of said bi-layer.
- 20. (Previously presented) The EUV reticle of claim 17, wherein said at least one layer of silicon forms one layer of said bi-layer and wherein beryllium forms another layer of said bi-layer.